

2023 年度新應材獎學金實施辦法

膏、目的:

新應材股份有限公司(以下簡稱本公司),為培育半導體材料人才並針對大學院校勤奮好學、品學兼優學生提供此獎學金,並延攬人才加入新應材之工作行列將其培育成為未來產業優秀人才,特訂定本辦法。

貳、申請資格:

- 一、國立台灣大學、國立清華大學、國立陽明交通大學、國立成功大學、國立中央大學、 國立中正大學、國立中興大學、國立中山大學、國立高雄大學、國立臺北科技大學、 國立高雄科技大學、中原大學、淡江大學、義守大學化學/化工/材料等相關系所。
- 二、 本國籍及外籍碩士生(碩一、碩二及預備研究生皆可申請)。
- 三、 前一學年操行成績及學業成績平均80分以上,大學畢業總成績平均75分以上。
- 四、 未享有公費及未領取其他獎學金者(外籍生免除此項限制)。

參、報名時間:

- 一、 自本辦法公告之日起至民國 112 年 11 月 3 日截止(書面資料繳交截止時間)。
- 二、 如獎學金名額已額滿,則提前截止。

肆、獎學金名額:

總計14名,各校預計錄取1名,若該校有缺額,名額將跨校系使用。

伍、獎學金金額:

- 一、 碩一生:審查合格者,每名每學期發放新台幣 60,000 元整,4期,共240,000 元。
- 二、 碩二生、(4+1)預備研究生:審查合格者,每名每學期發放新台幣 60,000 元整,2期, 共 120,000 元。

陸、審查標準及流程:

- 一、 初審:書面審查。備齊書面資料如下(將應備書面資料依序排列,並掃描為 PDF 檔, 檔名:學校系所-年級-名字,例:xx 大學 xx 所-碩一-王小明,**寄至聯絡窗口之電子** 郵箱):
 - (一) 新應材獎學金申請表。
 - (二)成績單正本。
 - ◆碩一:檢附台灣大專院校歷年成績單乙份。
 - ◆碩二:檢附台灣大專院校歷年成績單及研究所歷年成績單各乙份。
 - (三)履歷、自傳(300~500字,含未來展望)。
 - (四)學生證影本。
 - (五)身分證正反面影本。
 - (六)加分項目:其他有利於審查之文件。 (各類技能及語文檢定、專題研究、期刊 論文、相關證照)
- 二、 複審:初審通過者將由本公司通知安排面試。
- 三、 公告錄取:經本公司複審核定通過並公告錄取之學生(下稱「獎助生」,須於通知 發送一個月內完成「新應材碩士生獎學金保證書」之簽約手續,否則視同放棄。

柒、報名方式:

- 一、 統一將報名資料掃描為 PDF 檔寄至以下新應材聯絡窗口之電子郵箱。
- 二、 如報名過程有任何疑問,請聯繫新應材窗口負責人:

◆聯絡窗口:HR

◆電話分機: 03-4072100 #3153 #3229 ◆電子郵箱: recruit@aemc.com.tw

捌、獎學金權利及義務說明:

- 一、 本獎學金第一期獎助金於簽約後一個月內撥付,第二期後之獎助金於每學期開學後三個 月內由本公司撥款至獎助生提供之帳戶。
- 二、 獎助生應於畢業或退伍後三十日內郵寄履歷通知上述窗口,將其畢業或退伍一事告知 本公司,以利本公司安排其聘用事宜。並於約定報到日至新應材履約任職。
- 三、 獎助生履約任職將以「研發工程師/製程工程師」職務進行履約,履約期間薪資待遇福利將比 照本公司同等學歷之員工聘用規定敘薪及晉升 (高於就業服務法規定之面議薪資,會依學經 歷核敘薪級)。
- 四、 約定服務年限:
 - (一) 碩一生:自任職日起算2年。
 - (二) 碩二生、(4+1)預備研究生:自任職日起算1年。
- 五、 獎助生於每學期初提供在校證明及成績單。
- 六、 畢業後履約期間於公司內未通過新人適評者或違反公司管理規範屬重大情節者,將依 履約比例退回補助獎學金。

玖、獎助權利解除條件:

獎助生若發生以下事由之一時,本公司得經書面通知獎助生後提前終止或解除獎學金補助, 獎助生應於收到此書面通知後返還已受領之全部獎學金:

- 一、有轉學、休學、退學或約定修業期限屆滿仍未完成學業及取得學位者。但如獎助生經本 公司同意其休學(期間不逾一年者),則不在此限。休學次數以一次為限。
- 二、洩漏本公司及關係企業之機密資訊。
- 三、修習表現不佳,在學期間必修科目有一科(含)以上不及格者。
- 四、於在學期間違反校規或行為有妨礙本公司聲譽或校譽之虞,經輔導後仍未改善者。
- 五、於在學期間或服役期間有違反法令、行為有悖於善良風俗者。
- 六、未履行第捌條獎學金義務者。

拾、其他:

新應材股份有限公司保有最終修改、變更、解釋及取消本辦法之權利。

拾壹、公司官網:<u>https://www.aemc.com.tw/。</u>



2023 AEMC Scholarship Application Guidelines

1. Purpose:

This scholarship is provided by Advanced Echem Materials Company Ltd. (AEMC, here in after referred to as "the Company") to support diligent and outstanding master's students. The goals are to nurture talents in the field of semiconductor materials, attract students to join AEMC 's workforce, and foster future leaders. These guidelines outline the rules governing the execution of the scholarship.

2. Eligibility:

- a. Students majoring in chemistry, chemical engineering, materials, or related fields from the following universities: National Taiwan University, National Tsing Hua University, National Yang Ming Chiao Tung University, National Cheng Kung University, National Central University, National Chung Cheng University, National Chung Hsing University, National Sun Yat-sen University, National University of Kaohsiung, National Taipei University of Technology, National Kaohsiung University of Science and Technology, Chung Yuan Christian University, Tamkang University, and I-SHOU University.
- b. This scholarship is open to both Taiwanese and foreign master's students (first-year, second-year, and master 4+1 program students).
- c. Applicants must have attained a minimum average of 80% in academic and conduct performance during the previous academic year and graduated from a university with an overall score of 75%.

3. Application Period:

- a. The application period runs from the announcement of these guidelines until November 3, 2023 (deadline for submitting written materials).
- b. The application window will close earlier if the available scholarship slots are filled.

4. Scholarship Quota:

A total of 14 scholarships will be awarded, with each university being allocated one scholarship slot. If a university's quota remains unfilled, the remaining spots will be distributed among other eligible schools.

5. Scholarship Amount:

- a. First-year master's students: Qualified candidates will receive NT\$60,000 per semester, totaling NT\$240,000 over four semesters.
- b. Second-year master's students, and master 4+1 program students: Qualified candidates will receive NT\$60,000 per semester, totaling NT\$120,000 over two semesters.

6. Review Criteria and Process:

- a. Initial Review: Document screening. Applicants must submit the following documents in order as a combined PDF to the contact window's email address. The PDF file should follow this naming format: School Department-Grade-Name (e.g., XX University-MS First Jeff Lin).
 - AEMC Scholarship Application Form.
 - Official transcript.
 - First-year master's students: Transcripts for each year of undergraduate studies in Taiwan.
 - Second-year master's students: Transcripts for each year of undergraduate and graduate studies in Taiwan.
 - Resume and autobiography (300-500 words, including future goals).
 - Photocopy of the student ID card.
 - Photocopy of both sides of the ID card.
 - Supplementary documents: Additional documents supporting the review (certificates highlighting skills and language proficiency, research projects, journal papers, and other related certifications).
- b. Final Review: Applicants who pass the initial review will be notified to schedule an interview with the Company.

c. Announcement of Selection: Students who pass the Company's final review and are selected as scholarship recipients ("scholars") must sign the AEMC Master's Scholarship Agreement within one month of notification, otherwise the scholarship offer will be considered forfeited.

7. Application Process:

- a. Combine all application documents into a single PDF and email to the AEMC contact address below.
- b. For any inquiries during the application process, please contact the AEMC contact person:
 - Contact Window: HR
 - Phone Extension: 03-4072100 #3153 #3229
 - Email: recruit@aemc.com.tw

8. Scholarship Rights and Obligations:

- a. The first scholarship payment will be issued within one month after signing the agreement. Subsequent payments will be made by the Company to the scholar's account within three months after the start of each semester.
- b. Scholars must send their resume to the above contact window within 30 days of completing military service or graduating to inform the Company for employment arrangements and fulfill their commitment to join the Company on the agreed-upon reporting date.
- c. Scholars will be employed as "R&D Engineers or Manufacturing Engineers" during the service term. Their salary and benefits will comply with the Company's hiring policies for equivalent academic qualifications, including salary adjustments and promotion considerations (salaries will be surpass those stipulated in the Employment Services Act and will be determined based on academic background and work experience).
- d. Duration of Service Term:
 - First-year master's students: 2 years from the commencement of employment.
 - Second-year master's students, and master 4+1 program students: 1 year from the commencement of employment.
- e. Scholars should provide proof of enrollment and transcripts at the beginning of each semester.
- f. Following graduation, if a scholar fails to pass the probation period or violates the Company's management regulations during the service term, the scholarship granted must be reimbursed proportionally.

9. Scholarship Termination Conditions:

In the event of the following circumstances, the Company holds the right to terminate or revoke the scholarship in advance with written notice to the scholar. The scholar is liable to reimburse the scholarship amount received upon receipt of the written notice:

- a. Transferring to another school, taking a leave of absence, withdrawing from school, or failing to complete studies and secure a degree within the program duration. However, this limitation does not apply if the leave of absence, for a duration of up to one year, is approved by the Company. A single leave of absence is permissible.
- b. Disclosing confidential information belonging to the Company and its affiliated entities.
- c. Demonstrating poor academic performance, with one or more failing grades in required courses during a semester.
- d. Violating school rules or engaging in misconduct that damages the reputation of the Company or the school during the study period, without improvement after counseling.
- e. Violating laws or exhibiting unethical behavior during studies or military service.
- f. Failing to meet the scholarship obligations as stated in Article 8.

10. Miscellaneous:

AEMC reserves the right to make final modifications, changes, interpretations, and cancellations of these guidelines.

11. Company Website:

https://www.aemc.com.tw/ •



新應材獎學金申請表

收件日期(由公司填寫): 年 月 日

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		基本	資料					
姓名		學校			年級			
系 所		學號			學制	□日間	引 □夜	間
身份證字號		性別	□男□	女	出生年月日	年	月	H
聯絡電話			電子郵	件				
戶籍地址								
通訊地址								
	是否領取公	含量及其他獎	學金者	□是	□否			
		學歷	背景					
教育程度	學校名稱	學校名稱 主修科系 起迄年月						
大學					~			
高中			~					
檢附文件資料								
□新應材獎學金申請表(本表)。								
□成績單正本(依新應材獎學金實施辦法規定提供)。								
□履歷、自傳(300~500 字,含未來展望。)								
□學生證影本。								
□身分證正反面影本。								
□加分項目:其	□加分項目:其他有利於審查之文件。 (各類技能及語文檢定、專題研究、期刊論文、相關證照)						登照)	
個人資料蒐集告知聲明同意書								
 一、本人已詳讀新應材獎學金實施辦法各項說明及填寫相關內容,保證以上填寫資料均屬事實。 二、本人同意新應材基於獎學金申請之目的得對本人所提供之個人資料加以蒐集、處理及利用,獲獎者之學校系所及姓名將公佈於新應材公司官網;亦明瞭本人依法有向新應材請求查詢、閱覽、複製、補充、更正、刪除或請求停止蒐集、處理、利用個人資料之權,未獲獎者申請資料將保留至申請年年底以密件刪除、銷毀。 三、本同意書如有未盡事宜,本公司將依個人資料保護法或其他相關法規及其後修訂之規定辦理。 □您瞭解此一同意書符合個人資料保護法及相關法規之要求,且瞭解其內容,並同意本同意書所列之事項。 本人簽名: □田期: 								

成績單正本	

成績單正本

履歷

自傳(300~500 字,含未來展望。)

	身分證
正面	反面
	學生證
正面	反面
加分項目:其他有利於審查之文件。 (名	各類技能及語文檢定、專題研究、期刊論文、相關證照)

加分項目:其他有利於審查之文件。	(各類技能及語文檢定、專	專題研究、期刊論文 <i>、</i>	相關證照)



AEMC Scholarship Application Form

Date of Receipt (To be filled out by the Company): Y M D

			Basic Info	ormation					
Name			School			Grade			
Degree/Major			udent ID Iumber			Program Type	□Day □Nig		ool
Passport No.	Gender		Gender	□Male □Female		Date of Birth	Υ	М	D
Mobile Phone				Email Add	dress				
Nationality									
Present Address									
Language skills: English : Mandarin Chinese Other	□ basic level e: □ basic level : □ basic level	` □ i	ntermediat	e level 🕆 🗆 :	advanc	ed level			
			Educ	ation					
Education	Name of School Degree/Major From and To								
University	~								
High School		~							
Attached Supporting Documents									
□AEMC Scholarship Application Form									
□Official transcrip	ot (Provided in ac	corda	nce with A	EMC's Scho	larship	Application G	uidelin	es) '	>
□Resume and autobiography (300-500 words, including future goals).									
□Photocopy of the student ID card.									
□Photocopy of both sides of the ID card.									
□Supplementary documents: Additional documents supporting the review (certificates highlighting									
skills and language	skills and language proficiency, research projects, journal papers, and other related certifications)						ns)		
Personal Data Collection Consent Form									
1. I have read the explanations and completed the relevant sections of AEMC's Scholarship Application Guidelines, and I confirm that the information I have provided above is factual. 2. I agree that AEMC may collect, process, and use the personal information I provided for the purpose of the scholarship application. Scholarship recipients' names and departments will be published on AEMC's official website. I understand that, by law, I have the right to request access, review, copy, supplement, correct, delete, or stop the collection, processing, and use of my personal information. Application materials from non-recipients will be treated as confidential and retained until the end of the application year before being deleted and destroyed. 3. For matters not covered in this agreement, the Company will act in accordance with the Personal Data Protection Act or other relevant laws and their subsequent revisions. 3. You understand that this agreement complies with the requirements of the Personal Data Protection Act and related regulations. I also comprehend its content and consent to the matters listed in this agreement. 4. Applicant Signature: 4. App									
						Date:			

Official transcript

Official transcript

Resume	

Autobiography (300-500 words, including future goals)

ID card	
Front Side	Reverse Side
Student ID card.	
Front Side	Reverse Side
Supplementary documents: Additional documents supporting the review (certificates highlighting skills and language proficiency, research projects, journal papers, and other related certifications)	

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